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(54) **ROTARY ATTENUATOR AND METHOD OF MAKING IT**

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(2), (4) Date: **May 20, 2003**
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PCT Pub. Date: **Jun. 6, 2002**

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(51) **Int. Cl.**
H01P 1/22 (2006.01)

(52) **U.S. Cl.** ..... **333/81 A**; 327/308

(58) **Field of Classification Search** ..... 333/81 R, 333/81 A; 327/306, 308
See application file for complete search history.

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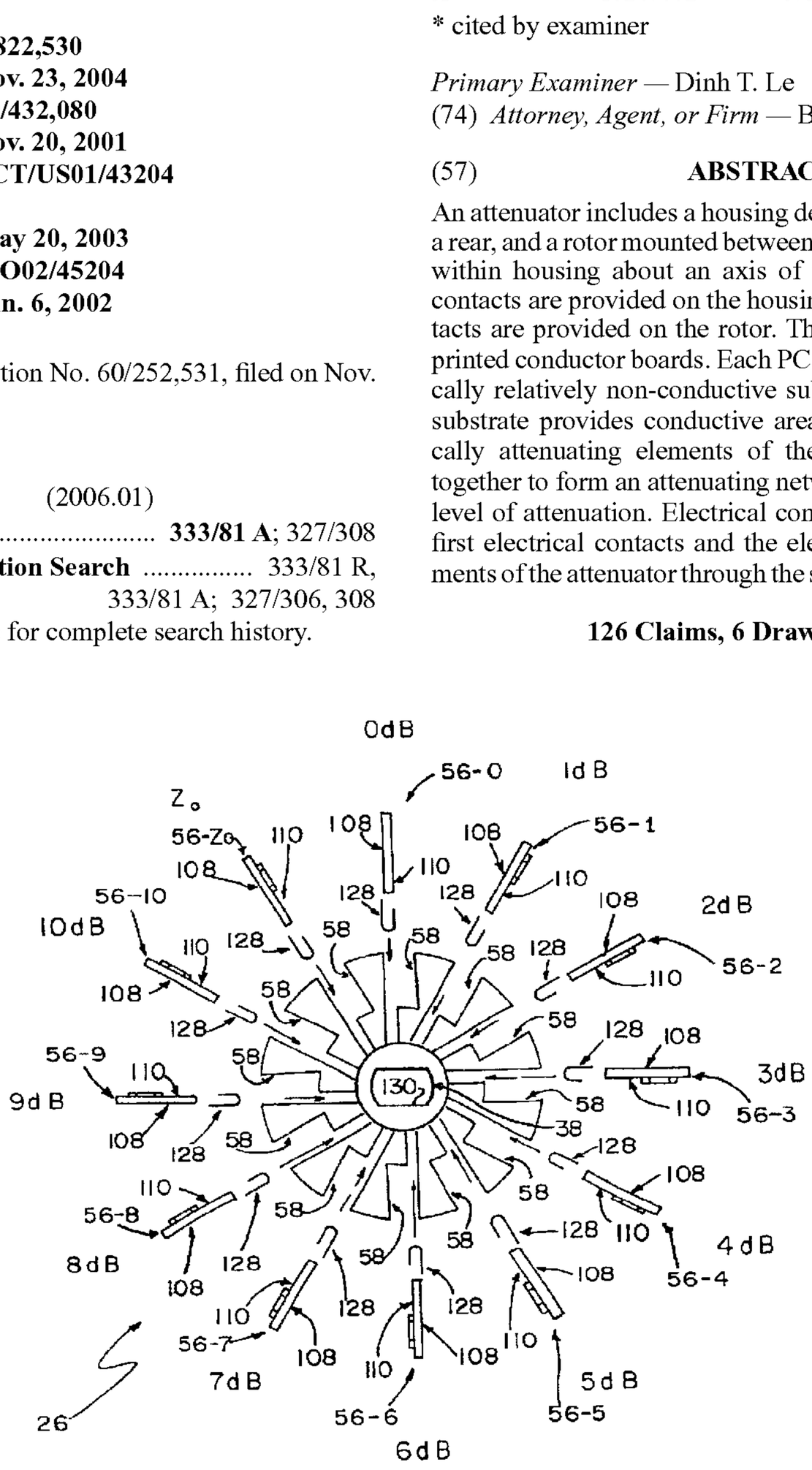
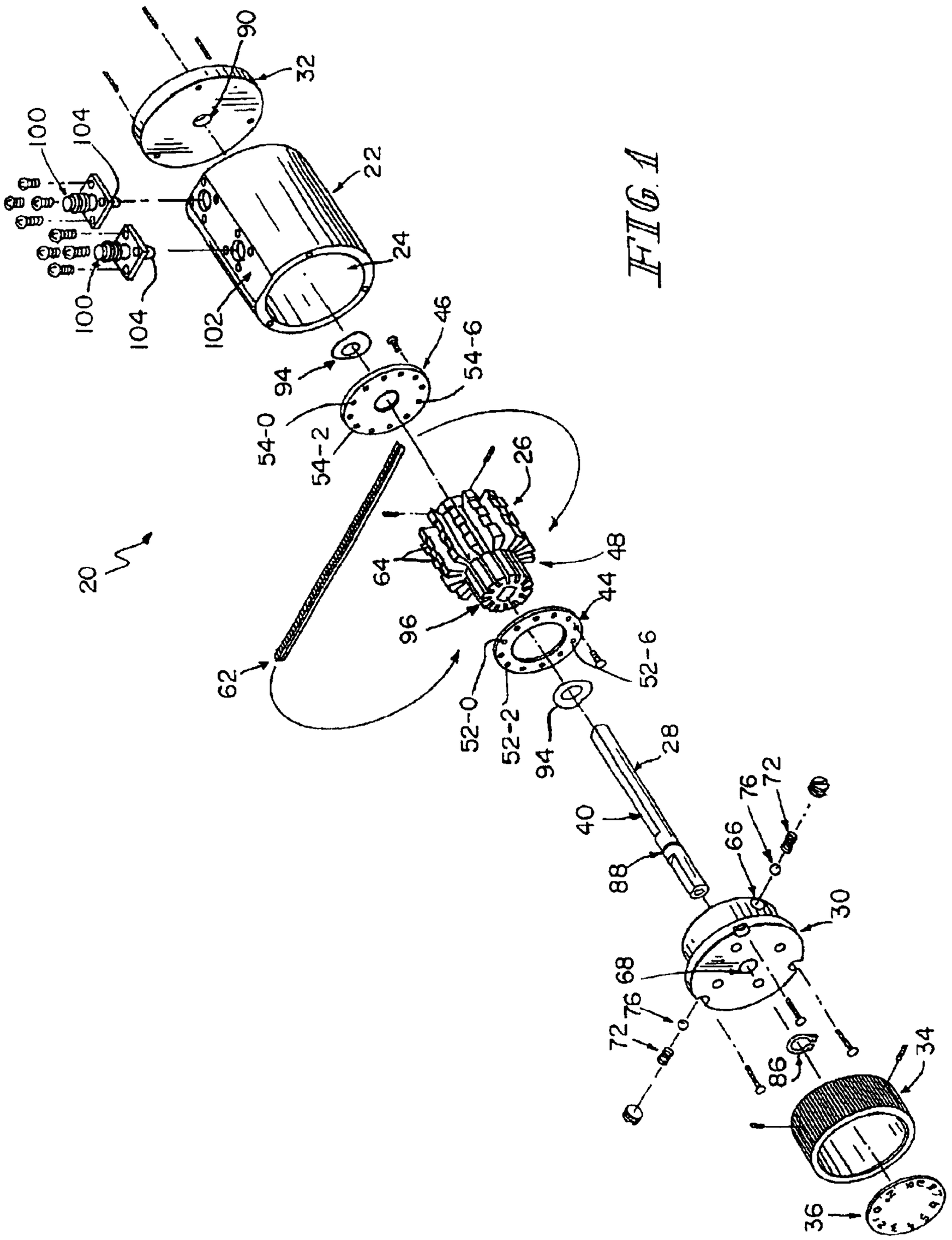
(74) *Attorney, Agent, or Firm* — Barnes & Thornburg LLP

(57) **ABSTRACT**

An attenuator includes a housing defining an interior, a front, a rear, and a rotor mounted between front and rear for rotation within housing about an axis of the rotor. First electrical contacts are provided on the housing. Second electrical contacts are provided on the rotor. The rotor includes multiple printed conductor boards. Each PC board includes an electrically relatively non-conductive substrate. One side of each substrate provides conductive areas through which electrically attenuating elements of the attenuator are coupled together to form an attenuating network providing a selected level of attenuation. Electrical contact is made between the first electrical contacts and the electrically attenuating elements of the attenuator through the second electrical contacts.

126 Claims, 6 Drawing Sheets

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54-2
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62
52-6
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34
36

FIG. 1

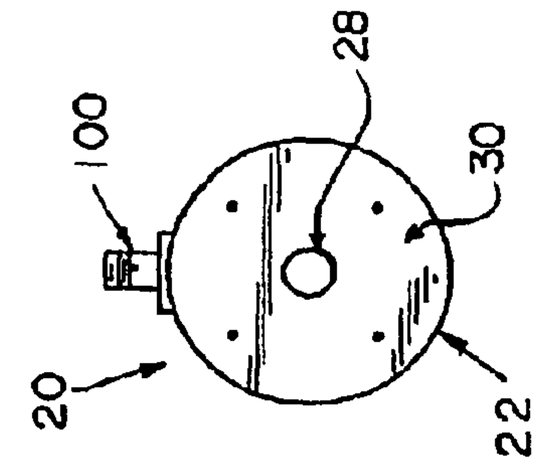


FIG. 3

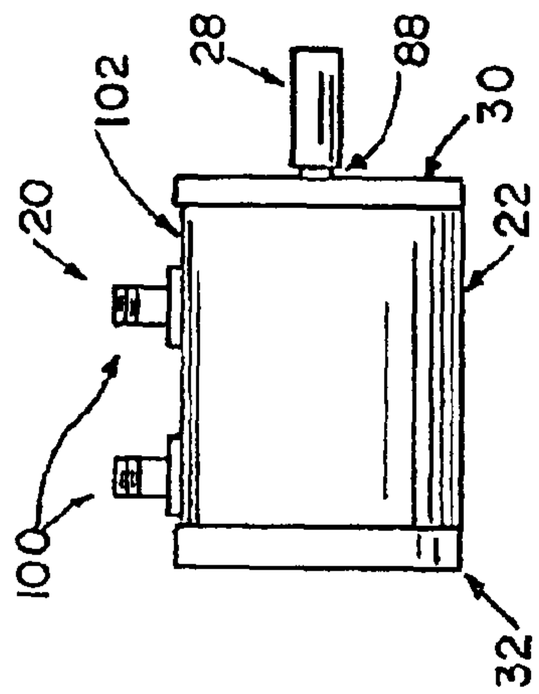


FIG. 2

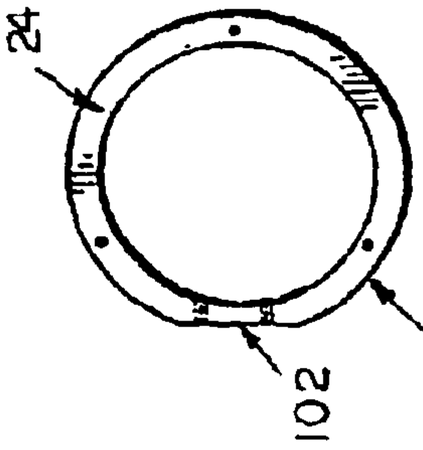


FIG. 6

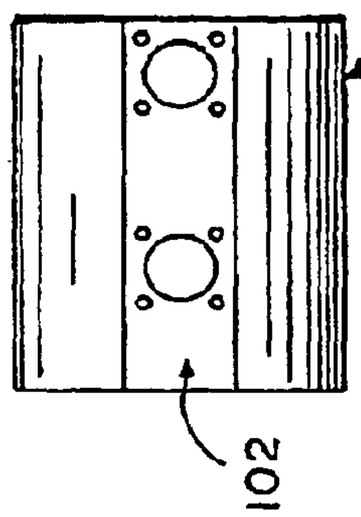


FIG. 5

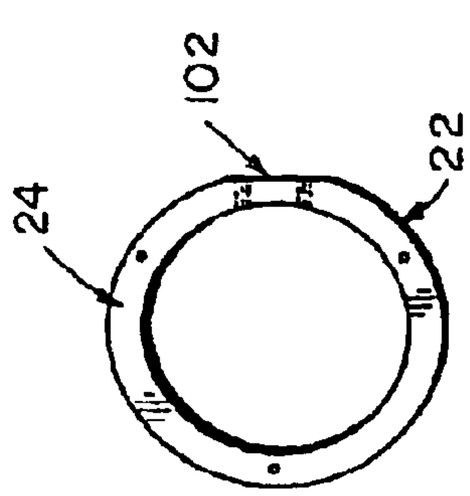


FIG 4

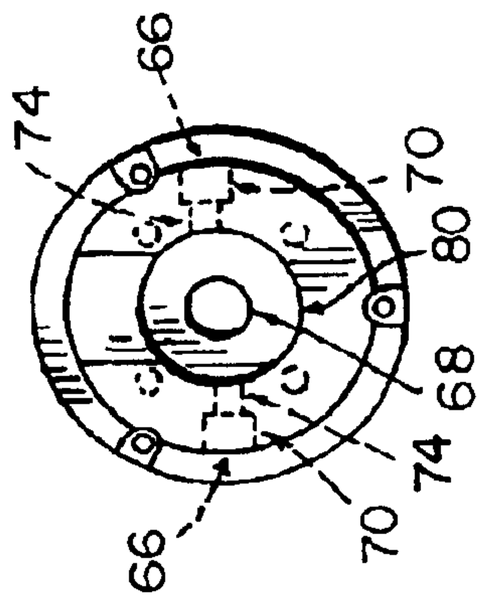


FIG 9

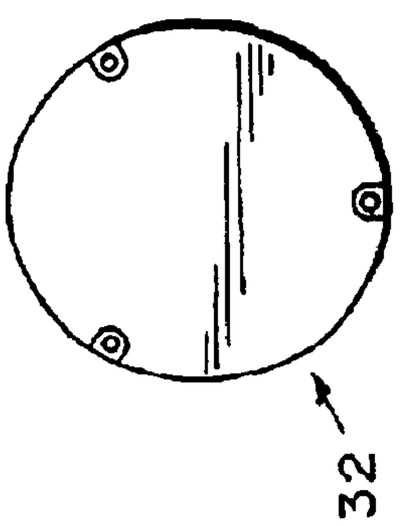


FIG 12

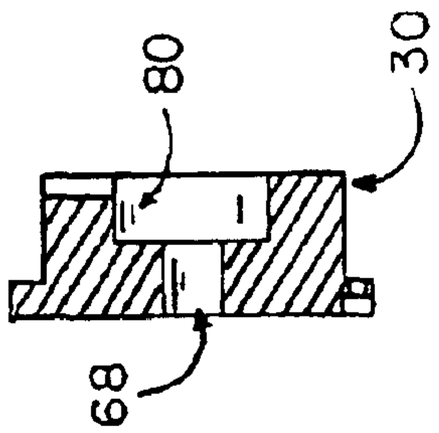


FIG 8

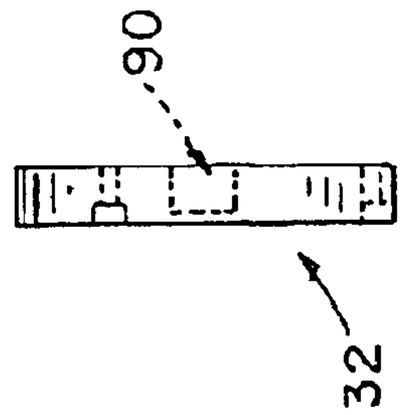


FIG 11

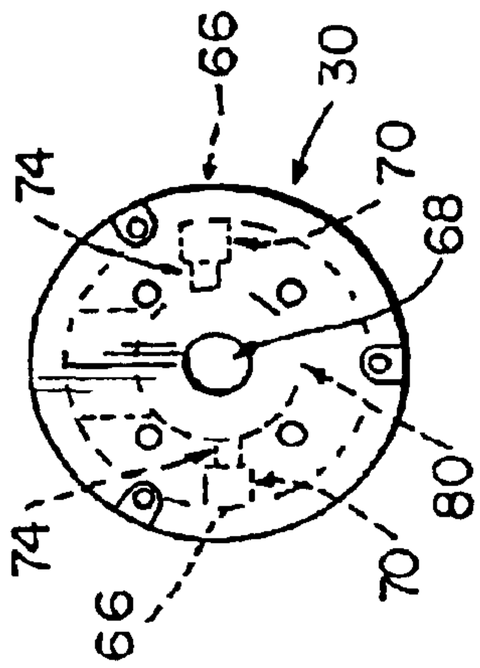


FIG 7

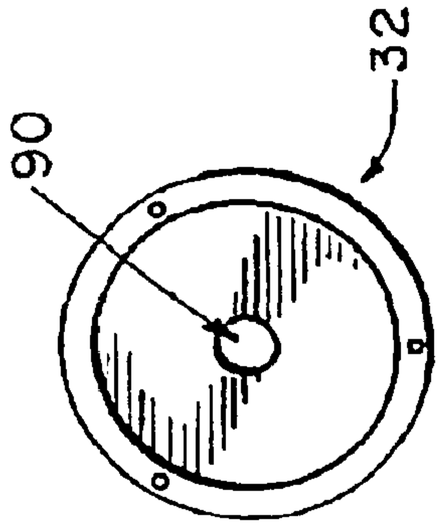
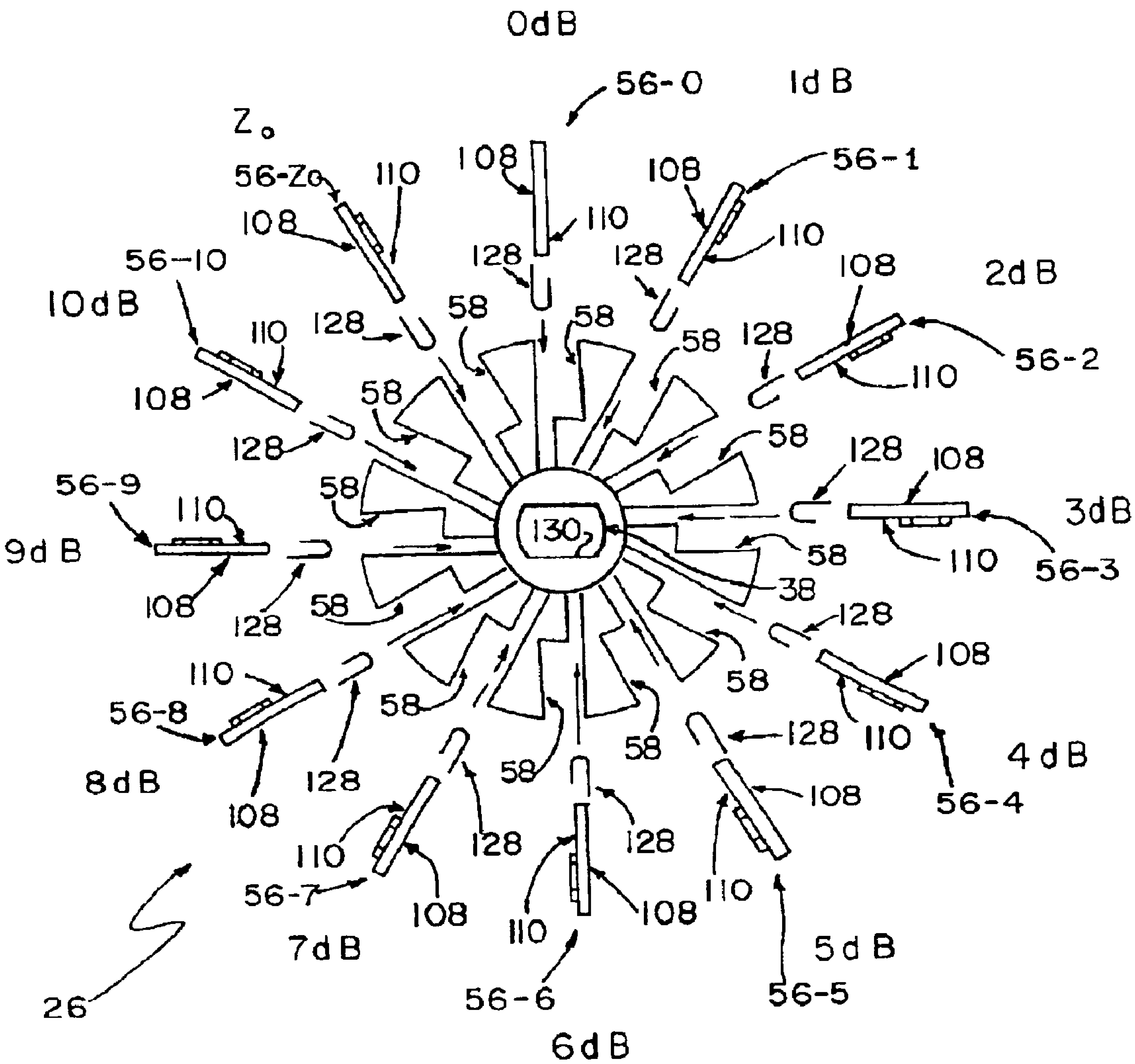


FIG 10


0dB
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1dB
Zo
56-Zo
110
108
56-1
108
110
108
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110
128
56-10
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2dB
110
128
58
128
58
58
56-2
108
128
110
58
58
128
128
108
56-9
58
110
130
3dB
9d B
58
110
108
128
58
38
56-3
128
58
110
108
56-8
58
128
110
58
58
4 dB
8dB
128
108
56-4
128
128
108
110
108
56-7
108
110
108
110
7dB
5d B
26
56-6
56-5
6dB

FIG. 13

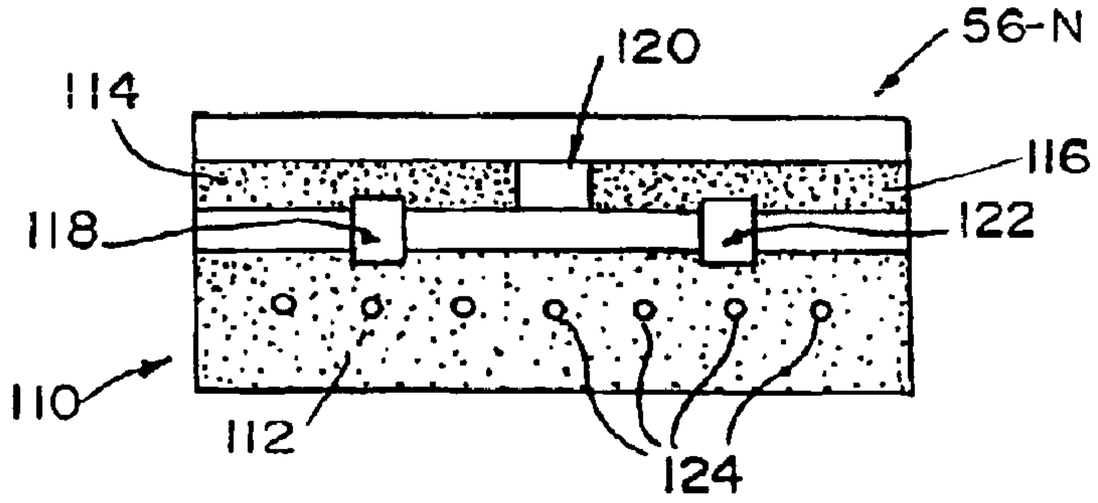


FIG. 14A

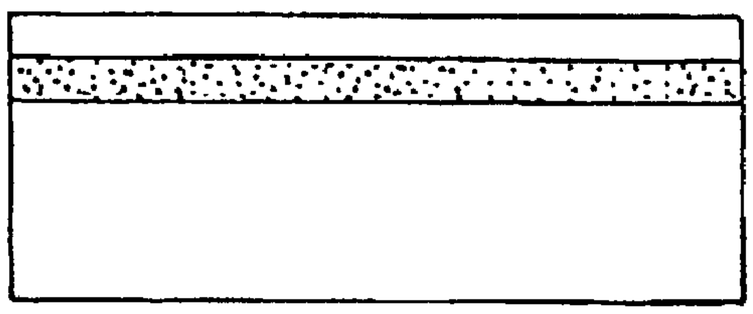


FIG. 14B

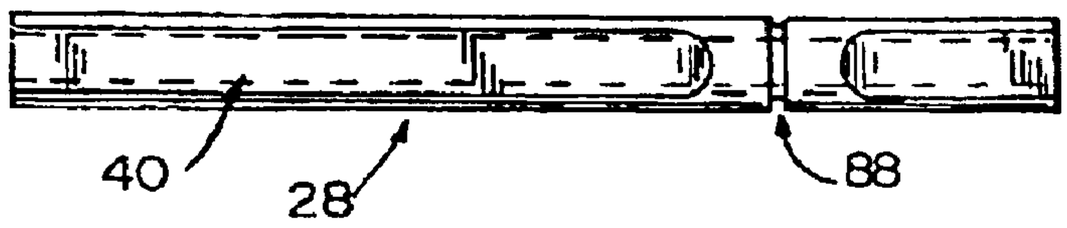


FIG. 15

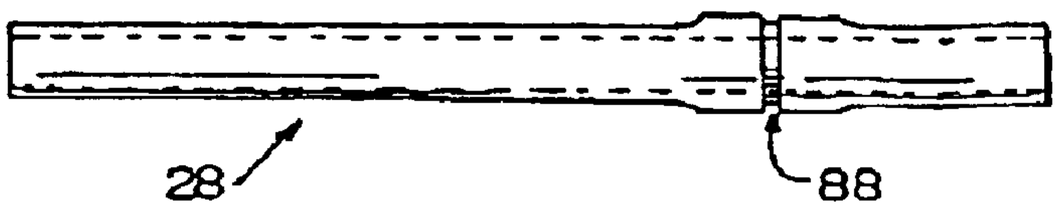


FIG. 16

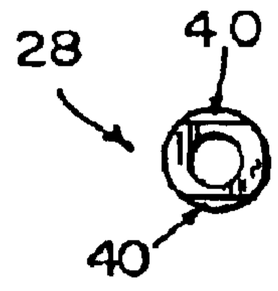
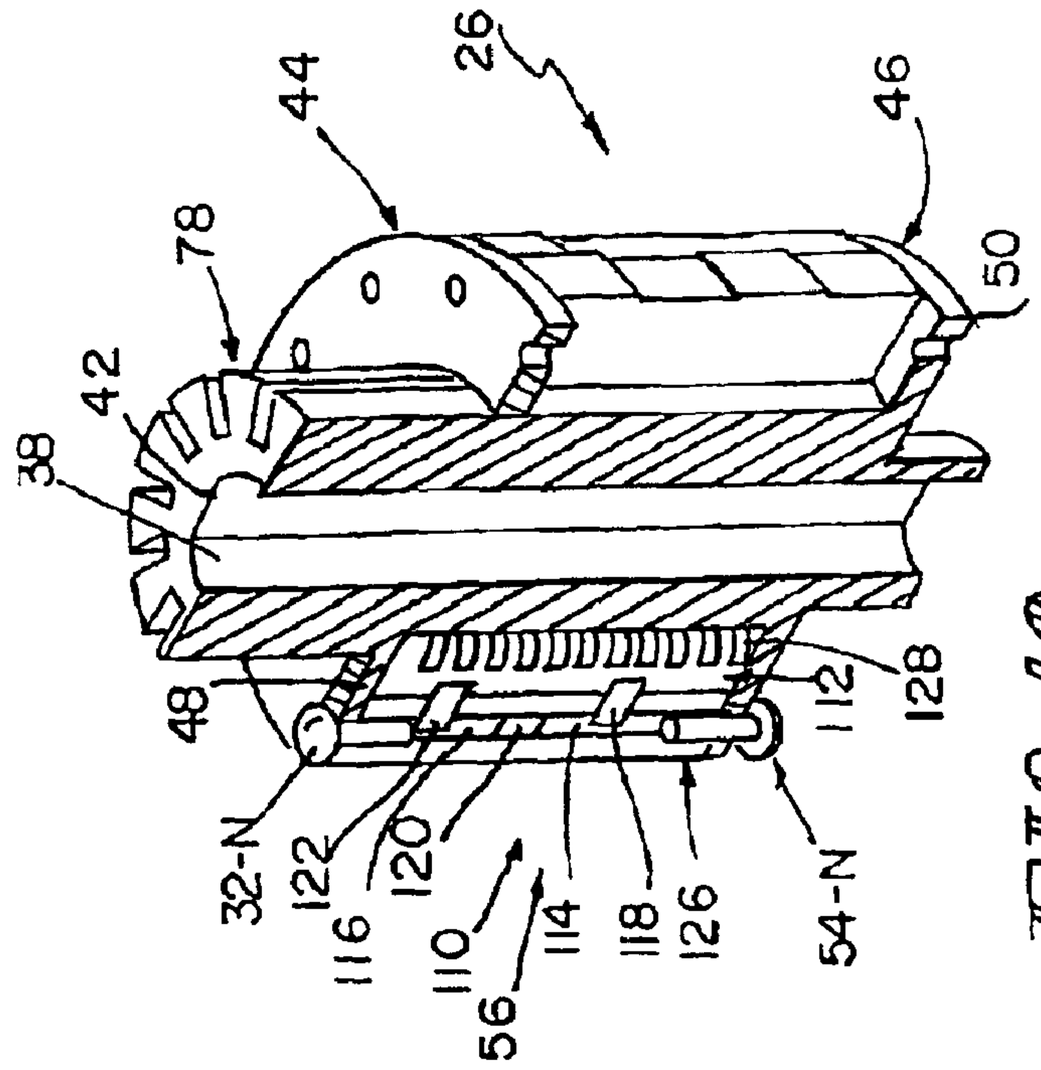


FIG. 17


26
44
46
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54-N

FIG 1A

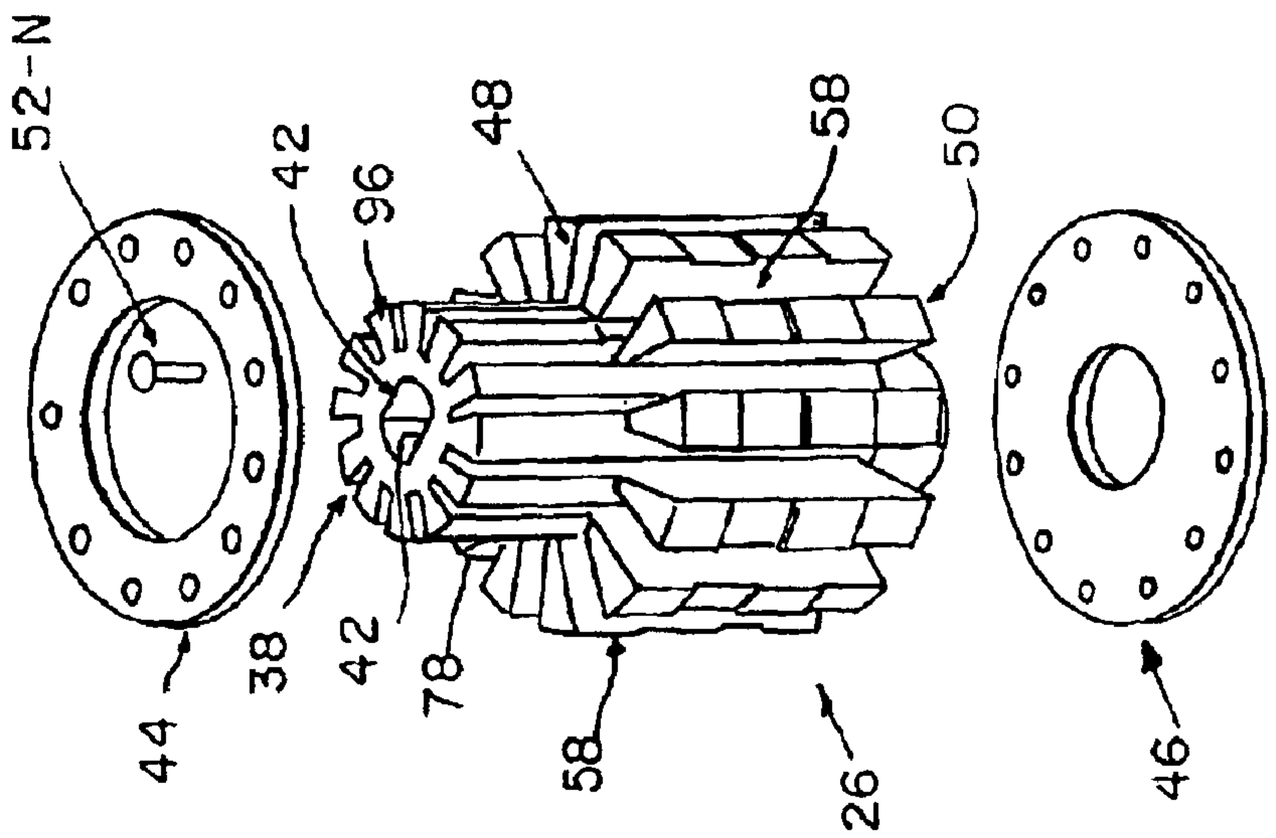
52-N
42
96
48
58
50
44
38
42
78
58
26
46

FIG 1B

ROTARY ATTENUATOR AND METHOD OF MAKING IT

Matter enclosed in heavy brackets [ ] appears in the original patent but forms no part of this reissue specification; matter printed in italics indicates the additions made by reissue.

CROSS-REFERENCE TO RELATED APPLICATIONS

This is a regular utility patent application claiming priority to U.S. Ser. No. 60/252,531 filed Nov. 22, 2000, titled Rotary Attenuator, and assigned to the same assignee as this application. The disclosure of U.S. Ser. No. 60/252,531 is hereby incorporated herein by reference.

FIELD OF THE INVENTION

This invention relates to rotary attenuators, and particularly to a robust, inexpensive rotary attenuator and a method of making it. Various types of attenuators are known. There are, for example, the attenuators illustrated and described in the following U.S. Pat. Nos. Re. 29,018; 3,626,352; 3,702,979; 3,750,078; 3,805,209; 3,858,128; 3,984,793; 4,001,736; 4,107,634; 4,117,425; 4,146,853; 4,222,066; 4,684,905; and, 4,695,811. The disclosures of these patents are hereby incorporated herein by reference. No representation is intended by this listing that a complete search of all relevant prior art has been conducted, or that there are no better references than the above listed patents, or that any of the above listed patents is material to patentability. Nor should any such representation be inferred.

BACKGROUND OF THE INVENTION

Rotary attenuators having printed wiring boards are known. The boards of these attenuators are typically constructed from alumina ceramic substrate and like low loss materials. Other rotary attenuators have conductors printed or otherwise provided on low loss ceramic. Some low loss ceramic board attenuators are known whose boards snap into the attenuator body, for example, into the rotor of the attenuator. The ceramic boards and the springs which hold them into the attenuator are rather expensive.

DISCLOSURE OF THE INVENTION

According to the invention, an attenuator includes a housing defining an interior. A rotor is mounted for rotation within the housing about an axis of the rotor. First electrical contacts are provided on the housing. Second electrical contacts are provided on the rotor, along with multiple printed conductor (PC) boards for engaging respective second electrical contacts. Each PC board includes an electrically relatively non-conductive substrate. A first side of each PC board is provided with electrically relatively conductive areas and electrically relatively non-conductive areas. Electrically attenuating elements are coupled together in attenuating networks with the electrically relatively conductive areas. The attenuating networks provide selected levels of attenuation. Electrical contact is selectively made between the first electrical contacts and selected attenuating networks through the second electrical contacts.

Illustratively according to the invention, the interior is generally right circular cylindrical.

Further illustratively according to the invention, the attenuator includes an index for indicating the position of rotor within housing.

Additionally illustratively according to the invention, the attenuator includes a shaft. The rotor includes a passageway for receiving the shaft. The shaft and passageway are provided with complementary features which mate when shaft is received in the passageway.

Illustratively according to the invention, the housing includes a front closure and a rear closure. At least one of the front closure and rear closure is removably attached to the housing.

Further illustratively according to the invention, the rotor includes axially oppositely facing surfaces constructed from electrically relatively non-conductive materials. The second electrical contacts are provided on the axially oppositely facing surfaces.

Additionally illustratively according to the invention, the axially oppositely facing surfaces are surfaces of resin substrates.

Further illustratively according to the invention, the attenuator includes a detent for promoting orientation of the rotor with selected ones of the second electrical contacts in electrical contact with respective first electrical contacts.

Further illustratively according to the invention, the attenuator includes at least one groove in one of the outer perimeter of the rotor and the interior of the housing, and at least one resilient, electrically relatively conductive contact strip oriented in the groove.

Illustratively according to the invention, each PC board further includes a second side which is electrically relatively conductive. One of the electrically relatively conductive areas on the first side of each PC board is electrically coupled to the second side of that respective PC board.

Additionally illustratively according to the invention, the electrically attenuating elements include surface mount resistors.

Illustratively according to the invention, the electrically attenuating elements of the attenuator are coupled between respective conductive areas.

Additionally illustratively according to the invention, the electrically attenuating elements include surface mount resistors.

Illustratively according to the invention, the rotor includes an outer surface provided with slots which extend generally radially and axially of the outer surface. Each slot is wide enough in a circumferential direction around the outer surface of rotor to receive edgewise a respective one of the PC boards.

Further illustratively according to the invention, each PC board includes an electrically relatively conductive side. Multiple strips of resilient electrically conductive material capture the radially inner edges of respective PC boards. The respective strips of resilient electrically conductive material make electrical contact with the electrically relatively conductive side of a respective respective PC board, with one of the conductive areas of a respective PC board, and with the rotor.

Additionally illustratively according to the invention, each electrically relatively non-conductive substrate includes fiber reinforced resin.

Illustratively according to the invention, the resin is fiber reinforced.

Further illustratively according to the invention, the electrically relatively non-conductive substrate includes fiber reinforced resin.

Additionally illustratively according to the invention, the fiber reinforced resin is fiberglass.

Illustratively according to the invention, the attenuator housing is constructed from extruded aluminum.

Further illustratively according to the invention, the attenuator housing is constructed from aluminum tubing.

BRIEF DESCRIPTION OF THE DRAWINGS

The invention may best be understood by referring to the following detailed description and accompanying drawings which illustrate the invention. In the drawings:

FIG. **1** illustrates an exploded perspective view of an attenuator constructed according to the invention;

FIG. **2** illustrates a side elevational view of the attenuator illustrated in FIG. **1**;

FIG. **3** illustrates an end elevational view of the attenuator illustrated in FIGS. **1-2**;

FIG. **4** illustrates an end elevational view of a component of the attenuator illustrated in FIGS. **1-3**;

FIG. **5** illustrates a side elevational view of the component illustrated in FIG. **4**;

FIG. **6** illustrates an end elevational view of the other end of the component, an end view of which is illustrated in FIG. **4**;

FIG. **7** illustrates an end elevational view of a component of the attenuator illustrated in FIGS. **1-3**;

FIG. **8** illustrates a sectional side elevational view of the component illustrated in FIG. **7**, taken generally along section lines **8-8** of FIG. **7**;

FIG. **9** illustrates an end elevational view of the other end of the component, an end view of which is illustrated in FIG. **7**;

FIG. **10** illustrates an end elevational view of a component of the attenuator illustrated in FIGS. **1-3**;

FIG. **11** illustrates a side elevational view of the component illustrated in FIG. **10**;

FIG. **12** illustrates an end elevational view of the other end of the component, an end view of which is illustrated in FIG. **10**;

FIG. **13** illustrates an end elevational view of a component of the attenuator illustrated in FIGS. **1-3**;

FIGS. **14**A-B illustrate side elevational views of components of the attenuator illustrated in FIGS. **1-3**;

FIG. **15** illustrates a top plan view of a component of the attenuator illustrated in FIGS. **1-3**;

FIG. **16** illustrates a side elevational view of the component illustrated in FIG. **15**;

FIG. **17** illustrates an end elevational view of the component illustrated in FIGS. **15-16**;

FIG. **18** illustrates a perspective view of certain components of the attenuator illustrated in FIGS. **1-3** during a stage of assembly; and,

FIG. **19** illustrates a sectional perspective view of certain components of the attenuator illustrated in FIGS. **1-3** during a stage of assembly subsequent to the stage illustrated in FIG. **18**.

DETAILED DESCRIPTION OF AN ILLUSTRATIVE EMBODIMENT

As used in this application, terms such as "electrically relatively conductive" and "electrically relatively non-insulative" refer to a broad range of conductivities electrically more conductive than materials described as "electrically relatively non-conductive" and "electrically relatively insulative." Terms such as "electrically semiconductive" refer to a broad range of conductivities between electrically relatively conductive and electrically relatively non-conductive.

FR 4 is a fairly ubiquitous, non-low loss, epoxy resin-impregnated fiberglass. However, since the present application proposes to use it in rotary attenuators, its loss characteristics are relatively inconsequential. The present application also proposes to use relatively inexpensive attenuator housing, front cover, back cover and rotor components, such as, for example, die cast zinc. The attenuator housing can even be constructed from, for example, extruded aluminum tubing. Additional cost savings are realized by employing solderless, snap-in technology to attach the boards to the rotor. Of course, the attenuator resistors need to be soldered to the board, but this is the case with many types of attenuator boards known in the art. Attenuators according to the present invention have been constructed having various step attenuation values, for example, 0-100 dB in 10 dB increments and 0-10 dB in 1 dB increments.

Turning now to the drawings, an attenuator **20** includes a housing **22** defining a generally right circular cylindrical interior **24**. A rotor **26** is mounted on a shaft **28** rotatably journalled in a front cover **30** and a rear cover **32** for rotation within housing **22** by rotation by an operator of a knob **34** mounted on the end of shaft **28** which projects through front cover **30**. Knob **34** may be provided with a suitable index **36** to the position of rotor **26** within housing **22**. The shaft **28** and a central passageway **38** through rotor **26** can be provided with complementary features **40**, **42**, such as flats, a longitudinally extending tongue and groove, or the like, which mate when shaft **28** is inserted through passageway **38** to insure that rotation of shaft **28** causes rotation of rotor **26**.

Rotor **26** front **44** and back **46** plates, respectively, are provided on the axially facing front and back surfaces **48**, **50**, respectively, of rotor **26**. Plates **44**, **46** are constructed from electrically non-conductive materials such as thin sheets of fiber reinforced resin or the like, but are provided with electrical contacts **52-0**, **52-1**, **52-2**, . . . **52-10**, **52-Z_0**, **54-0**, **54-1**, **54-2**, . . . **54-10**, **54-Z_0**, respectively, through which electrical contact is made to electrical traces on printed circuit (hereinafter sometimes PC) boards **56-0**, **56-1**, **56-2**, . . . **56-10**, **56-Z_0**, respectively, mounted in respective slots **58** on rotor **26**, as will be discussed later. Electrical contact between the body of rotor **26** and housing **22** is promoted by spring finger contact strips **62** (only one of which is illustrated in FIG. **1** for purposes of clarity), known in the art, which are oriented in grooves **64** around the circumference of rotor **26**.

Front cover **30** is provided with two radial bores **66** which are oriented generally diametrically opposite one another with respect to the bore **68** for receiving the shaft **28**. Each of bores **66** includes a larger diameter region **70** for housing a detent spring **72** and a smaller diameter region **74** for housing a detent ball **76**. A smaller diameter forward region **78** of rotor **26** is received in a somewhat cup-like enlarged rear region **80** of the bore **68**. This cup-like region **80** intersects the bores **66**, so that the detent balls **76** engage the forward extensions of radially and axially extending grooves **58** formed in rotor **26** to receive respective ones of the PC boards **56-0**, **56-1**, **56-2**, . . . **56-10**, **56-Z_0**.

The rotor **26** and shaft **28** assembly is captured axially in housing **22** by sliding the assembled front cover **30** on the shaft **28**, snapping a locking ring **86** into a circumferential groove **88** on shaft **28**, and mounting the front cover **30** on the housing **22**, illustratively using threaded fasteners. The shaft **28** is then inserted into a blind shaft-receiving bore **90** in the rear cover **32**, and the rear cover **32** is mounted on the housing **22**, again, illustratively, using threaded fasteners. Spring tension washers **94** may be provided between each end of rotor **26** and the adjacent face **96**, **50** of the rotor **26**, respectively, to help position the rotor **26** in the housing **22** and promote rotation of it.

Means are provided for making electrical contact with the PC boards **56-0**, **56-1**, **56-2**, . . . **56-10**, **56**-Z_0 carrying the various attenuator combinations. In the illustrated embodiment, these means include two coaxial connectors **100** mounted on a flat **102** provided for this purpose on the outside of housing **22**. Spring wiper blades **104** electrically connected to the center contacts (not shown) of respective ones of these connectors **100** are configured to contact respective electrical contacts **52-0**, **52-1**, **52-2**, . . . **52-10**, **52**-Z_0, **54-0**, **54-1**, **54-2**, . . . **54-10**, **54**-Z_0, when the action of the detents **58**, **66**, **70**, **72**, **74**, **76** stops rotation of the rotor **26** with those contacts **52-0**, **52-1**, **52-2**, . . . **52-10**, **52**-Z_0, **54-0**, **54-1**, **54-2**, . . . **54-10**, **54**-Z_0, in positions to be contacted by wiper blades **104**. Coaxial connectors **100** are also mounted to housing **22** by suitable means, illustratively, threaded fasteners, which insures the electrical connection of the outer conductors of connectors **100** with housing **22**, and components electrically connected to housing **22**.

Turning now to the configuration of PC boards **56-0**, **56-1**, **56-2**, . . . **56-10**, **56**-Z_0, and their assembly into rotor **26**, each PC board **56-0**, **56-1**, **56-2**, . . . **56-10**, **56**-Z_0 includes a side **108** which is metallized to provide a ground plane and a circuit trace side **110** which is only partially metallized to provide the conductive pads **112**, **114**, **116** by which the resistors **118**, **120**, **122** which form the various stages of attenuation provided by the network **112**, **114**, **116**, **118**, **120**, **122** are coupled together in an attenuating network **112**, **114**, **116**, **118**, **120**, **122** configuration. One, **112**, of the conductive pads **112**, **114**, **116** is coupled by plated through holes **124** to the ground plane on the other side **108** of the PC board **56-0**, **56-1**, **56-2**, . . . **56-10**, **56**-Z_0. The other two conductive pads **114**, **116** are soldered to the shanks **126** of respective contacts **52-0**, **52-1**, **52-2**, . . . **52-10**, **52**-Z_0, **54-0**, **54-1**, **54-2**, . . . **54-10**, **54**-Z_0 on the front and back plates **44**, **46**, respectively. Chip resistors **118** are connected, for example, by soldering, to pads **112** and **114** of each PC board **56** to complete the various selectable attenuating networks **112-0**, **114-0**, **116-0**, **118-0**, **120-0**, **122-0**, **112-1**, **114-1**, **116-1**, **118-1**, **120-1**, **122-1**, **112-2**, **114-2**, **116-2**, **118-2**, **120-2**, **122-2**, . . . **112-10**, **114-10**, **116-10**, **118-10**, **120-10**, **122-10**, **112**-Z_0, **114**-Z_0, **116**-Z_0, **118**-Z_0, **120**-Z_0, **122**-Z_0. Chip resistors **120** are connected between pads **114** and **116** of each PC board **56**. Chip resistors **122** are connected between pads **112** and **116** of each PC board **56**. Illustrative resistance values in ohms to permit selection of attenuations from 0 dB to 10 dB or to terminate both of connectors 100 with ~50 Ω impedances are illustrated in the following table.

Attenuation in dB	Value of resistor 118 in ohms	Value of resistor 120 ohms	Value of resistor 122 in ohms
0	N/A	N/A	N/A
1	866	5.62	866
2	432	11.5	432
3	294	17.8	294
4	221	23.7	221
5	178	30.1	178
6	150	37.4	150
7	130	44.2	130
8	115	52.3	115
9	105	61.9	105
10	95.3	71.5	95.3
Z_o	49.9	∞	49.9

During assembly of the various PC boards **56-0**, **56-1**, **56-2**, . . . **56-10**, **56**-Z_0 into respective slots **58** on rotor **26**, several segments **128** of spring finger contact strip **62** material

are broken from a strip and are slipped over what will become the radially innermost edge of each PC board **56-0**, **56-1**, **56-2**, . . . **56-10**, **56**-Z_0, so that the segments make good electrical contact with the ground planes on sides **108** of PC boards **56-0**, **56-1**, **56-2**, . . . **56-10**, **56**-Z_0, with pads **112** on the opposite sides of PC boards **56-0**, **56-1**, **56-2**, . . . **56-10**, **56**-Z_0, and with rotor **26**. Then, using a zero indicator mark **130** on rotor **26** for orientation, the various PC boards **56-0**, **56-1**, **56-2**, . . . **56-10**, **56**-Z_0 are pressed into their respective slots **58** in rotor **26**.

What is claimed is:

1. An attenuator including a housing defining an interior, a rotor mounted for rotation within the housing about an axis of the rotor, first electrical contacts provided on the housing, second electrical contacts being provided on the rotor, and multiple printed conductor (PC) boards for engaging respective second electrical contacts, each PC board including an electrically relatively non-conductive substrate, a first side of each PC board providing electrically relatively conductive areas and electrically relatively non-conductive areas, electrically attenuating elements coupled together in attenuating networks with the electrically relatively conductive areas, the attenuating networks providing selected levels of attenuation, electrical contact being selectively made between the first electrical contacts and selected attenuating networks through the second electrical contacts.

2. The apparatus of claim **1** wherein the interior is generally right circular cylindrical.

3. The apparatus of claim **1** further including an index for indicating the position of *the* rotor within *the* housing.

4. The apparatus of claim **1** further including a shaft, the rotor including a passageway for receiving the shaft, the shaft and passageway being provided with complementary features which mate when the shaft is received in the passageway.

5. The apparatus of claim **1** wherein the housing includes a front closure and a rear closure, at least one of the front closure and rear closure being removably attached to the housing.

6. The apparatus of claim **1** wherein the rotor includes axially oppositely facing surfaces constructed from electrically relatively non-conductive materials, the second electrical contacts being provided on the axially oppositely facing surfaces.

7. The apparatus of claim **6** wherein the axially oppositely facing surfaces are surfaces of resin substrates.

8. The apparatus of claim **6** further including a detent for promoting orientation of the rotor with selected ones of the second electrical contacts in electrical contact with respective ones of the first electrical contacts.

9. The apparatus of claim **1** further including at least one groove in one of the outer perimeter of the rotor and the interior of the housing, and at least one resilient, electrically relatively conductive contact strip oriented in the groove.

10. The apparatus of claim **1** wherein each PC board further includes a second side which is electrically relatively conductive, one of the electrically relatively conductive areas on the first side of each PC board being electrically coupled to the second side of that respective PC board.

11. The apparatus of claim **1** wherein the electrically attenuating elements include surface mount resistors.

12. The apparatus of claim **1** wherein the electrically attenuating elements of the attenuator are coupled between respective conductive areas.

13. The apparatus of claim **12** wherein the electrically attenuating elements include surface mount resistors.

14. The apparatus of claim **1** wherein the rotor includes an outer surface provided with slots which extend generally radially and axially of the outer surface, each slot being wide enough in a circumferential direction around the outer surface of *the* rotor to receive edgewise a respective one of the PC boards.

15. The apparatus of claim **14** wherein each PC board further includes an electrically relatively conductive side and further including multiple strips of resilient electrically conductive material, each strip capturing the radially inner edge of a respective PC board and making electrical contact with *the* electrically relatively conductive side of each PC board, with one of the conductive areas of each PC board, and with the rotor.

16. The apparatus of claim **14** wherein the electrically relatively non-conductive substrate includes resin.

17. The apparatus of claim **16** wherein the electrically relatively non-conductive substrate includes fiber reinforced resin.

18. The apparatus of claim **1** wherein the electrically relatively non-conductive substrate includes fiber reinforced resin.

19. The apparatus of claim **18** wherein the fiber reinforced resin is fiberglass.

20. The apparatus of claim **1** wherein the attenuator housing is constructed from extruded aluminum.

21. The apparatus of claim **1** wherein the attenuator housing is constructed from aluminum tubing.

22. The apparatus of claim 1 wherein the rotor is constructed from zinc.

23. The apparatus of claim 22 wherein the rotor is constructed from die cast zinc.

24. The apparatus of claim 1 wherein the rotor is die cast.

25. The apparatus of claim 2 wherein the rotor is constructed from zinc.

26. The apparatus of claim 25 wherein the rotor is constructed from die cast zinc.

27. The apparatus of claim 2 wherein the rotor is die cast.

28. The apparatus of claim 3 wherein the rotor is constructed from zinc.

29. The apparatus of claim 28 wherein the rotor is constructed from die cast zinc.

30. The apparatus of claim 3 wherein the rotor is die cast.

31. The apparatus of claim 4 wherein the rotor is constructed from zinc.

32. The apparatus of claim 31 wherein the rotor is constructed from die cast zinc.

33. The apparatus of claim 4 wherein the rotor is die cast.

34. The apparatus of claim 5 wherein the rotor is constructed from zinc.

35. The apparatus of claim 34 wherein the rotor is constructed from die cast zinc.

36. The apparatus of claim 5 wherein the rotor is die cast.

37. The apparatus of claim 6 wherein the rotor is constructed from zinc.

38. The apparatus of claim 37 wherein the rotor is constructed from die cast zinc.

39. The apparatus of claim 6 wherein the rotor is die cast.

40. The apparatus of claim 7 wherein the rotor is constructed from zinc.

41. The apparatus of claim 40 wherein the rotor is constructed from die cast zinc.

42. The apparatus of claim 7 wherein the rotor is die cast.

43. The apparatus of claim 8 wherein the rotor is constructed from zinc.

44. The apparatus of claim 43 wherein the rotor is constructed from die cast zinc.

45. The apparatus of claim 8 wherein the rotor is die cast.

46. The apparatus of claim 9 wherein the rotor is constructed from zinc.

47. The apparatus of claim 46 wherein the rotor is constructed from die cast zinc.

48. The apparatus of claim 9 wherein the rotor is die cast.

49. The apparatus of claim 10 wherein the rotor is constructed from zinc.

50. The apparatus of claim 49 wherein the rotor is constructed from die cast zinc.

51. The apparatus of claim 10 wherein the rotor is die cast.

52. The apparatus of claim 11 wherein the rotor is constructed from zinc.

53. The apparatus of claim 52 wherein the rotor is constructed from die cast zinc.

54. The apparatus of claim 11 wherein the rotor is die cast.

55. The apparatus of claim 12 wherein the rotor is constructed from zinc.

56. The apparatus of claim 55 wherein the rotor is constructed from die cast zinc.

57. The apparatus of claim 12 wherein the rotor is die cast.

58. The apparatus of claim 13 wherein the rotor is constructed from zinc.

59. The apparatus of claim 58 wherein the rotor is constructed from die cast zinc.

60. The apparatus of claim 13 wherein the rotor is die cast.

61. The apparatus of claim 14 wherein the rotor is constructed from zinc.

62. The apparatus of claim 61 wherein the rotor is constructed from die cast zinc.

63. The apparatus of claim 14 wherein the rotor is die cast.

64. The apparatus of claim 15 wherein the rotor is constructed from zinc.

65. The apparatus of claim 64 wherein the rotor is constructed from die cast zinc.

66. The apparatus of claim 15 wherein the rotor is die cast.

67. The apparatus of claim 16 wherein the rotor is constructed from zinc.

68. The apparatus of claim 67 wherein the rotor is constructed from die cast zinc.

69. The apparatus of claim 16 wherein the rotor is die cast.

70. The apparatus of claim 17 wherein the rotor is constructed from zinc.

71. The apparatus of claim 70 wherein the rotor is constructed from die cast zinc.

72. The apparatus of claim 17 wherein the rotor is die cast.

73. The apparatus of claim 18 wherein the rotor is constructed from zinc.

74. The apparatus of claim 73 wherein the rotor is constructed from die cast zinc.

75. The apparatus of claim 18 wherein the rotor is die cast.

76. The apparatus of claim 19 wherein the rotor is constructed from zinc.

77. The apparatus of claim 76 wherein the rotor is constructed from die cast zinc.

78. The apparatus of claim 19 wherein the rotor is die cast.

79. The apparatus of claim 20 wherein the rotor is constructed from zinc.

80. The apparatus of claim 79 wherein the rotor is constructed from die cast zinc.

81. The apparatus of claim 20 wherein the rotor is die cast.

82. The apparatus of claim 21 wherein the rotor is constructed from zinc.

83. The apparatus of claim 82 wherein the rotor is constructed from die cast zinc.

84. The apparatus of claim 21 wherein the rotor is die cast.

85. A method of making an attenuator comprising providing a housing defining an interior, mounting a rotor for rotation within the housing about an axis of the rotor, providing first electrical contacts on the housing, providing second electrical contacts on the rotor, and providing multiple printed conductor (PC) boards for engaging respective second electrical contacts, mounting the rotor for rotation within the housing including mounting a die cast rotor for rotation within the housing, the providing of the multiple PC boards includes providing on each PC board an electrically relatively non-conductive substrate, providing on a first side of each PC board electrically relatively conductive areas and electrically relatively non-conductive areas, and coupling electrically attenuating elements together in attenuating networks with the electrically relatively conductive areas to provide selected levels of attenuation.

86. The method of claim 85 wherein the providing of the housing defining the interior comprises providing a housing defining a generally right circular cylindrical interior.

87. The method of claim 85 further including providing an index for indicating the position of the rotor within the housing.

88. The method of claim 85 further including providing a shaft, and mounting the rotor for rotation within the housing about an axis of the rotor includes providing a passageway through the rotor for receiving the shaft and providing on the shaft and passageway complementary features which mate when the shaft is received in the passageway.

89. The method of claim 85 wherein the providing of the housing defining the interior includes providing a front closure and a rear closure, and removably attaching at least one of the front closure and rear closure to the housing.

90. The method of claim 85 wherein the mounting of the rotor for rotation within the housing about the axis of the rotor includes providing on the rotor axially oppositely facing surfaces constructed from electrically relatively non-conductive materials, and providing second electrical contacts on the rotor includes providing the second electrical contacts on the axially oppositely facing surfaces.

91. The method of claim 90 wherein the providing on the rotor of axially oppositely facing surfaces constructed from electrically relatively non-conductive materials includes providing on the rotor axially oppositely facing resin surfaces.

92. The method of claim 85 further including providing a detent for promoting orientation of the rotor with selected ones of the second electrical contacts in electrical contact with respective ones of the first electrical contacts.

93. The method of claim 85 further including providing at least one groove in one of the outer perimeter of the rotor and the interior of the housing, and at least one resilient, electrically relatively conductive contact strip oriented in the groove.

94. The method of claim 85 wherein the providing of the multiple PC boards includes providing multiple PC boards, each of which includes a second side which is electrically relatively conductive, and coupling one of the electrically relatively conductive areas on the first side of each PC board to the second side of that respective PC board.

95. The method of claim 85 wherein the coupling of the electrically attenuating elements together in attenuating networks with the electrically relatively conductive areas to provide selected levels of attenuation includes coupling surface mount resistors together in attenuating networks with the electrically relatively conductive areas to provide selected levels of attenuation.

96. The method of claim 85 wherein the coupling of the electrically attenuating elements together in attenuating networks with the electrically relatively conductive areas to provide selected levels of attenuation includes coupling the electrically attenuating elements of the attenuator between respective conductive areas.

97. The method of claim 96 wherein the coupling of the electrically attenuating elements together in attenuating networks with the electrically relatively conductive areas to provide selected levels of attenuation includes coupling surface mount resistors together in attenuating networks with the electrically relatively conductive areas to provide selected levels of attenuation.

98. The method of claim 85 wherein the mounting of the rotor for rotation within the housing includes providing on an outer surface of the rotor slots which extend generally radially and axially of the outer surface, each slot being wide enough in a circumferential direction around the outer surface of the rotor to receive edgewise a respective one of the PC boards.

99. The method of claim 85 wherein the providing of multiple PC boards for engaging respective second electrical contacts includes providing on each PC board an electrically relatively conductive side and providing multiple strips of resilient electrically conductive material, capturing with each strip the radially inner edge of a respective PC board and making electrical contact with the electrically relatively conductive side of each PC board, with one of the conductive areas of each PC board, and with the rotor.

100. The method of claim 85 wherein the providing on each PC board of the electrically relatively non-conductive substrate includes providing on each PC board a resin substrate.

101. The method of claim 100 wherein the providing on each PC board of the resin substrate includes providing on each PC board a fiber reinforced resin substrate.

102. The method of claim 85 wherein the providing on each PC board of the electrically relatively non-conductive substrate includes providing on each PC board a fiber reinforced resin substrate.

103. The method of claim 102 wherein the providing on each PC board of the fiber reinforced resin substrate includes providing on each PC board a fiberglass substrate.

104. The method of claim 85 wherein the providing of the housing defining an interior includes providing a housing constructed from extruded aluminum.

105. The method of claim 85 wherein the providing of the housing defining the interior includes providing a housing constructed from aluminum tubing.

106. The method of claim 85 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

107. The method of claim 86 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

108. The method of claim 87 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

109. The method of claim 88 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

110. The method of claim 89 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

111. The method of claim 90 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

112. The method of claim 91 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

113. The method of claim 92 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

114. The method of claim 93 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

115. The method of claim 94 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

116. The method of claim 95 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

117. The method of claim 96 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

118. The method of claim 97 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

119. The method of claim 98 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

120. The method of claim 99 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

121. The method of claim 100 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

122. The method of claim 101 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

123. The method of claim 102 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

124. The method of claim 103 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

125. The method of claim 104 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc-containing rotor for rotation within the housing about an axis of the rotor.

126. The method of claim 105 wherein the mounting of the die cast rotor for rotation within the housing about the axis of the rotor includes mounting a die cast zinc rotor for rotation within the housing about an axis of the rotor.

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